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PATENTS UNIT

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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):
**FURUKAWA, RYOICHI
SAKAI, SATOSHI
YAMAMOTO, SATOSHI**

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)

Name: **HITACHI, LTD.**

Address: **6, Kanda Surugadai 4-chome, Chiyoda-ku,
Tokyo, Japan**

3. Nature of conveyance:

MRP
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Assignment Merger
 Security Agreement Change of Name
 Other _____

Execution Date: **September 20, 24, 20, 2002.**

Other

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4. Application number(s) or patent number(s):
If this document is being filed together with a new application, the execution date of the application is: **September 20, 24, 20, 2002.**

A. Patent Application No.(s)
10288539

B. Patent Registration No.(s)

Additional number(s) attached Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **Antonelli, Terry, Stout & Kraus, LLP**

Internal Address:

**1300 North Seventeenth Street
Suite 1800
Arlington, VA 22209
USA**

City: State: Zip:

6. Total number of applications and patents involved **1**

7. Total fee (37 CFR 3.41)..... **\$40.00**

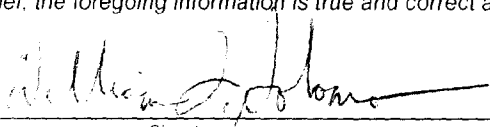
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To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

William I. Solomon, Reg# 28,565  **November 6, 2002**

Name of Person Signing Signature Date

Total number of pages including cover sheet, attachments, and document: **2**

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ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

METHOD FOR MANUFACTURING SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made:

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)

(発明者フルネームサイン)

Date Signed

(署名日)

1) <u>Ryoichi Furukawa</u> (Ryoichi FURUKAWA)	<u>20/September/2002</u>
2) <u>Satoshi Sakai</u> (Satoshi SAKAI)	<u>24/September/2002</u>
3) <u>Satoshi Yamamoto</u> (Satoshi YAMAMOTO)	<u>20/September/2002</u>
4) _____	_____
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____